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NOTES:

1. MATERIAL

i) HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V-0

ii) TERMINAL : COPPER ALLOY iii) HOLD DOWN: COPPER ALLOY

2. FÍNISH

i) TERMINAL : Au PLATING AT CONTACT POINT

MATT TIN PLATING 100u" MIN AT SOLDER TAIL WITH NICKEL 50u" MIN UNDERPLATE.

ii) HOLD DOWN: MATT TIN PLATING.

MATT TIN PLATING 100u" MIN AT SOLDER TAIL WITH NICKEL 50u" MIN UNDERPLATE.

3. THE HOUSING WILL WITHSTAND EXPOSURE TO 260 DEGREE C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFREA RED, OR VAPOR PHASE REFLOW OVEN.

4. Packaging spec. GS-14-840.

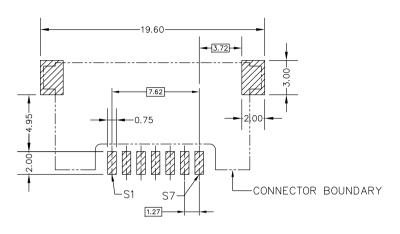
5. Prodcut Spec. GS-12-194.

6. Prodcut Spec. 110-634

10089036- 0 X X X LE LEAD FREE BLANK: SPEC AS NOTE 5 J: SPEC AS NOTE 6 1: G/F PLATING AT CONTACT 2: 15U" GOLD AT CONTACT 3: 30U" GOLD AT CONTACT

0: TAPE & REEL PACKING WITH PICK UP CAP

↑1: TAPE & REEL PACKING WITHOUT PICK UP CAP



RECOMMENDED MOUNTING LAYOUT RECOMMENDED PCB T: 1.6mm TOLERANCE UNLESS OTHERWISE ±0.1mm

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PDS: Rev:D

STATUS:Released Printed: Oct 03, 20

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